

BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS

wakefield-vette

BOARD LEVEL HEAT SINKS

D2PAK; TO-220; SOL-20

SURFACE MOUNT HEAT SINKS

217 SERIES



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SURFACE MOUNT HEAT SINKS

D2PAK; TO-220; SOT-223; SOL-20

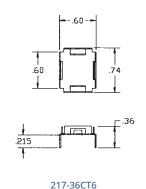
Compatible with surface mount technology (SMT) automated production techniques for ease of assembly and a variety of soldering methods, these heat sinks allow greater packaging densities and reduction in PC-board area, increasing the power dissipation of surface mount devices (SMDs) while maintaining and improving manufacturers' component thermal specifications.

FEATURES AND BENEFITS

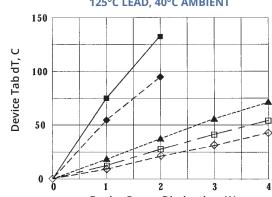
- No interface material is needed
- Copper with matte tin plating for improved solderability and assembly
- Both the component and the heat sink are installed on the PC-board utilizing standard SMT assembly equipment for "Tape & Reel" and "Tube" formats
- EIA standards and ESD protection are specified
- Can be used with water soluble or no clean SMT solder creams or other pastes

Footprint	Height Above				Thermal Performance at Typical Load			
Standard	PC Board	Dimensions	Package	Package	Natural	Forced		
P/N	in. (mm)	in. (mm)	Format	Quantity	Convection	Convection		
217-36CTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Bulk	1	55°C @ 1W	16.0°C/W @ 200 LFM		
217-36CTTE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tube	20	55°C @ 1W	16.0°C/W @ 200 LFM		
217-36CTRE6	.360 (9.1)	.600 (15.2) x .740 (18.8)	Tape & Reel	250	55°C @ 1W	16.0°C/W @ 200 LFM		
Material: Copper Matta Tip Plated								

MECHANICAL DIMENSIONS



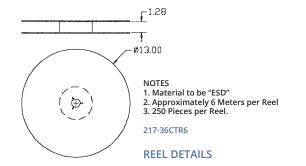
THERMAL PERFORMANCE 6 LAYER BOARD, D' PAK 125°C LEAD, 40°C AMBIENT

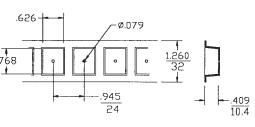




Device Power Dissipation. W KEY: \blacksquare Device only, NC \spadesuit Device + HS, NC \blacktriangle Device + HS, 100 lfm

Dimensions: in.

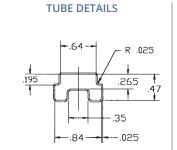


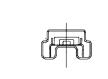


TAPE DETAILS

MECHANICAL DIMENSIONS

BOARD LAYOUT RECOMMENDATIONS

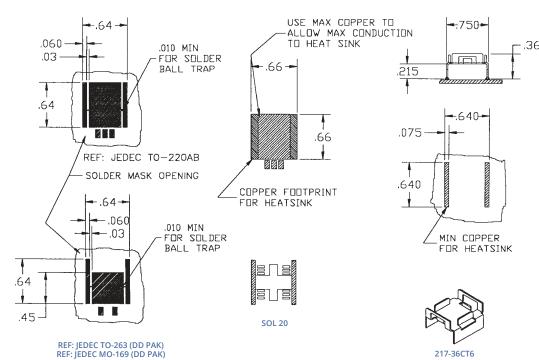




Tube: 16.25 Inches Long, Min. esd Material with Nail Stops 20 Pieces per Tube

217-36CTT6

Dimensions: in.



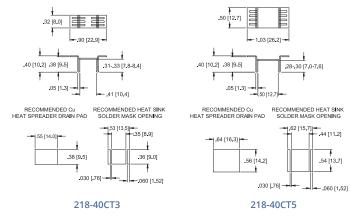
218 SERIES

SURFACE MOUNT HEAT SINK

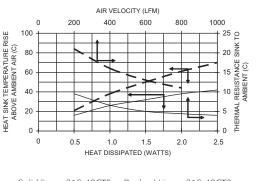
SMT Devices

Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load Natural Convection Forced Convection				
218-40CTE3 218-40CTE5	.40 (10.2) .40 (10.2)	.90 (22.9) x .315 (8.0) 1.03 (26.2) x .50 (12.7)	62°C rise @ 2W 62°C rise @ 2W	21°C/W @ 200LFM 21°C/W @ 200LFM			
Material: Copper Matte Tip Plated							

MECHANICAL DIMENSIONS



NATURAL AND FORCED **CONVECTION CHARACTERISTICS**



Solid line = 218-40CT5 Dashed Line = 218-40CT3

Contact us: (603) 635-2800 wakefield-vette.com